TE Internal #: 1735871-1

SAS, Receptacle, Wire-to-Board, 29 Position, 1 Row, 1 Port, Vertical, Surface Mount, .049 in [1.27 mm] Centerline, Power & Signal, Board

Mount

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Connectors > PCB Connectors > SAS & MiniSAS > PT30 XFP Connectors



SAS Connector Type: SAS

Connector & Housing Type: Receptacle

Connector System: Wire-to-Board

Number of Positions: 29

Number of Rows: 1

All PT30 XFP Connectors (15)

Features

Product Type Features

Shell	Without
SAS Connector Type	SAS
Connector & Housing Type	Receptacle
Connector System	Wire-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	29
Number of Rows	1
Number of Ports	1
PCB Mount Orientation	Vertical
Body Features	

Black

Primary Product Color



	30 μin
Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	1.5 A
Termination Features	
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	1.27 mm[.049 in]
Dimensions	
Profile Height from PCB	9.15 mm[.36 in]
Usage Conditions	
High Temperature Housing	Yes
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Power & Signal
Industry Standards	
PCIe/SAS Generation	Gen2
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	220
Packaging Method	Tape & Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant



China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought

















Documents

Product Drawings

SAS BACKPLANE RECEPT, VERTICAL, SMT

English

CAD Files

Customer View Model

ENG_CVM_CVM_1735871-1_A.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1735871-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1735871-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

English

Product Environmental Compliance

TE Material Declaration

English